



Material Content Data Sheet



Sales Product Name		BFR 840L3RHESD E6327		Issued		1. August 2018		
MA#		MA001623222						
Package		PG-TSLP-3-9		Weight*		0.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.14		1396	
	noble metal	gold	7440-57-5	0.003	0.54		5414	
	inorganic material	silicon	7440-21-3	0.024	4.77	5.45	47671	54481
leadframe	non noble metal	nickel	7440-02-0	0.131	26.06	26.06	260578	260578
wire	noble metal	gold	7440-57-5	0.009	1.85	1.85	18451	18451
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		306	
	organic material	carbon black	1333-86-4	0.003	0.61		6111	
	plastics	epoxy resin	-	0.042	8.25		82486	
	inorganic material	silicondioxide	60676-86-0	0.263	52.20	61.09	522109	611012
leadfinish	noble metal	gold	7440-57-5	0.011	2.11	2.11	21071	21071
plating	noble metal	silver	7440-22-4	0.017	3.44	3.44	34407	34407
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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